



#### PNP SILICON PLANAR HIGH PERFORMANCE TRANSISTOR IN SOT223

#### **Features**

- BV<sub>CEO</sub> > 60V
- Maximum continuous current I<sub>C(cont)</sub> = 3A
- Low Saturation Voltage
- Complementary Type FZT651
- Lead-Free Finish; RoHS compliant (Note 1)
- Halogen and Antimony Free. "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

SOT223

#### **Mechanical Data**

- Case: SOT223
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish
- Weight: 0.112 grams (approximate)

Green

Top View

Device Symbol



### Ordering Information (Notes 3 & 4)

Product	Grade	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
FZT751TA	Commercial	FZT751	7	12	1,000
FZT751QTA	Automotive	FZT751	7	12	1,000
FZT751TC	Commercial	FZT751	13	12	4,000
FZT751QTC	Automotive	FZT751	13	12	4,000

1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

 Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.</li>

3. For packaging details, go to our website at http://www.diodes.com.

4. Products with Q-suffix are automotive grade. Automotive products are electrical and thermal the same as the commercial, except where specified.

#### **Marking Information**

Notes:



FZT751 = Product Type Marking Code





## Maximum Ratings @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-80	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-60	V
Emitter-Base Voltage	V <sub>EBO</sub>	-5	V
Continuous Collector Current	lc	-3	А
Peak Pulse Current	I <sub>CM</sub>	-6	А

### Thermal Characteristics $@T_A = 25$ cunless otherwise specified

Characteristic	Symbol	Value	Unit	
Power Dissipation	(Note 5)	D_	2	W
Fower Dissipation	(Note 6)	FD	3	W
Thermal Registeres, Junction to Ambient	(Note 5)	Р	62.5	°C/W
Thermal Resistance, Junction to Ambient	(Note 6)	Keja	41.7	°C/W
Thermal Resistance, Junction to Leads (Note 7)		R <sub>θJL</sub>	12.93	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C	

Notes:

For devices mounted on 25mm x 25mm single sided 2oz weight copper, in still air conditions.
For devices mounted on 50mm x 50mm single sided 2oz weight copper, in still air conditions.

7. Thermal resistance from junction to solder-point (at the end of the collector lead)





## **Thermal Characteristics**







# Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-80	-	-	V	I <sub>C</sub> = -100μA
Collector-Emitter Breakdown Voltage (Note 8)	BV <sub>CEO</sub>	-60	-	-	V	I <sub>C</sub> = -10mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-5	-	-	V	I <sub>E</sub> = -100μA
Collector Cut off Current	I <sub>CBO</sub>	-	-	-0.1	μA	V <sub>CB</sub> = -60V
		-	-	-10		V <sub>CB</sub> = -60V, T <sub>amb</sub> = 100℃
Emitter Cut-off Current	I <sub>EBO</sub>	-	-	-0.1	μA	$V_{EB} = -4V$
Collector Emitter Seturation Voltage (Note 8)	N	-	-0.15	-0.3	V	$I_{\rm C} = -1A, I_{\rm B} = -100 {\rm mA}$
	VCE(sat)	-	-0.45	-0.6		I <sub>C</sub> = -3A, I <sub>B</sub> = -300mA
Base-Emitter Saturation Voltage (Note 8)	V <sub>CE(sat)</sub>	-	-0.9	-1.25	V	I <sub>C</sub> = -1A, I <sub>B</sub> = -100mA
Base-Emitter Turn-On Voltage (Note 8)	V <sub>BE(on)</sub>	-	-0.8	-1.0	V	$I_{C} = -1A, V_{CE} = -2V$
	h <sub>FE</sub>	70	200	-		I <sub>C</sub> = -50mA, V <sub>CE</sub> = -2V
DC Current Coin (Note 8)		100	200	300		I <sub>C</sub> = -500mA, V <sub>CE</sub> = -2V
DC Current Gain (Note 8)		80	170	-	-	$I_{C} = -1A, V_{CE} = -2V$
		40	150	-		$I_{C} = -2A, V_{CE} = -2V$
Current Gain-Bandwidth Product (Note 8)	fT	100	140	-	MHz	V <sub>CE</sub> = -5V, I <sub>C</sub> = -100mA f = 100MHz
Turn-On Time	t <sub>on</sub>	-	40	-	ns	V <sub>CC</sub> = -10V, I <sub>C</sub> = -500mA
Turn-Off Time	t <sub>off</sub>	-	450	-	ns	$I_{B1} = I_{B2} = -50 \text{mA}$
Output Capacitance (Note 8)	C <sub>obo</sub>	-	-	30	pF	$V_{CB} = -10V, f = 1MHz$

Notes: 8. Measured under pulsed conditions. Pulse width  $\leq$  300  $\mu s.$  Duty cycle  $\leq$  2%





## **Typical Characteristics**







# **Package Outline Dimensions**



## **Suggested Pad Layout**



Dimensions	Value (in mm)
X1	3.3
X2	1.2
Y1	1.6
Y2	1.6
C1	6.4
C2	2.3





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